/ Descriptions

WR0<5 ṂṂ Ƀ QSQ ÆṀ ч s ‖ ㄱ Silicon NPN transistor in a TO-92 Plastic Package.

/ Features

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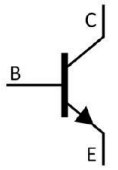
High transition frequency, low output capacitance.

/ Applications

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RF amplifier applications.

/ Equivalent Circuit



/ Pinning



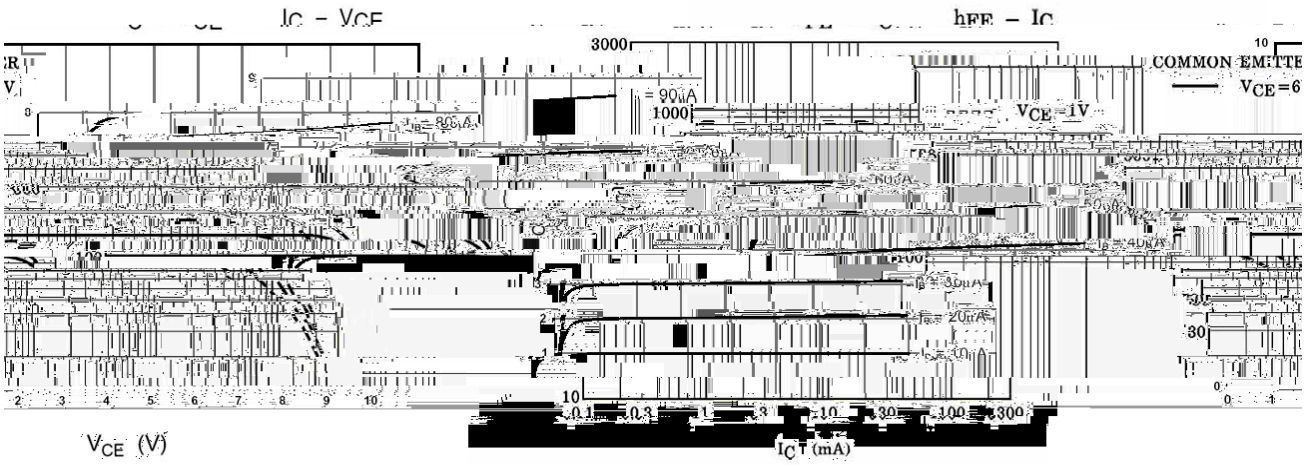
PIN1 χ Base PIN 2 χ Collector PIN 3 χ Emitter

/ hFE Classifications & Marking

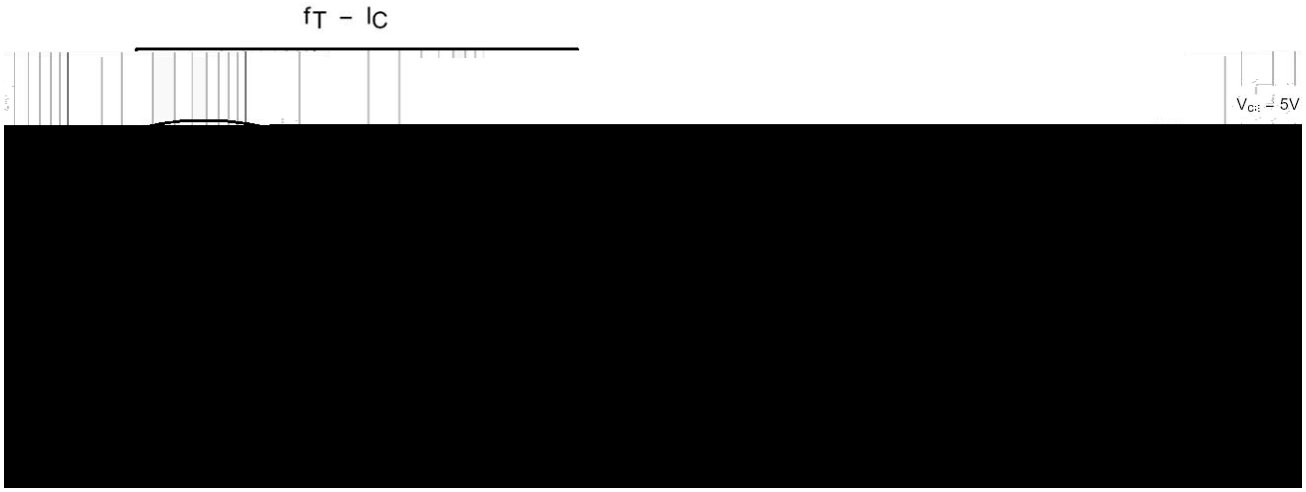
h_{FE} Classifications Symbol	R	O	Y
h_{FE} Range	40~80	70~140	120~240

v ‴Ω Parameter	ϒ N Symbol	‴Ω Ö Rating	D Ч Unit
Collector to Base Voltage	V_{CBO}	30	V
Collector to Emitter Voltage	V_{CEO}	20	V
Emitter to Base Voltage	V_{EBO}	4.0	V
Collector Current - Continuous	I_C		

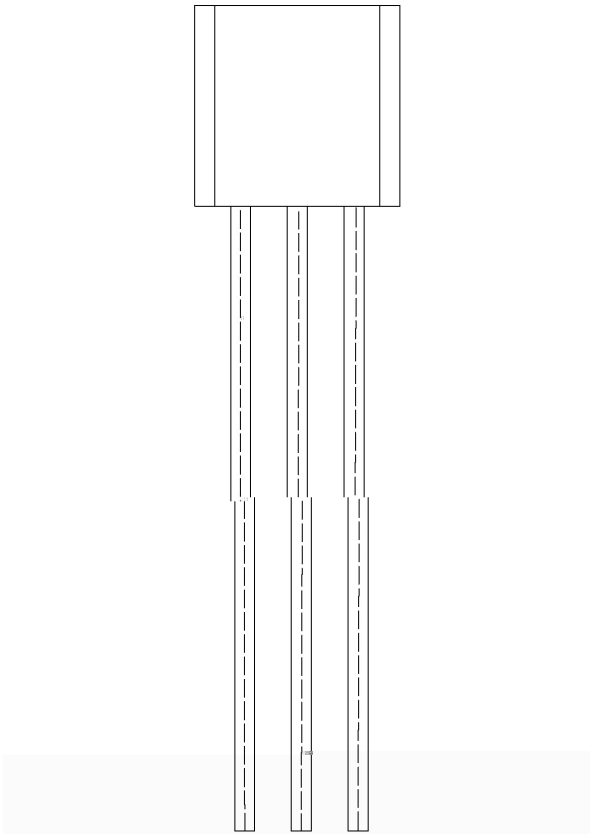
/ Electrical Characteristic Curve







/ Marking Instructions



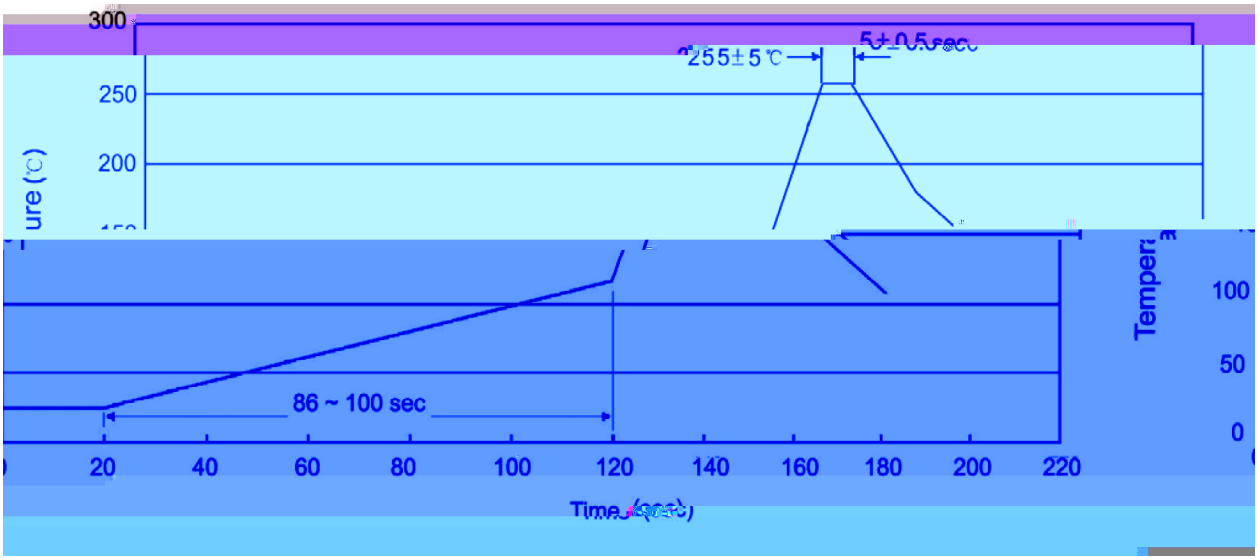
ب ˝ χ

EU=	ﻫ ڑ И Ґ
F8678 χ	ﻫ ڑ N Ґ
U=	ﻫ h_{FE} ‘ 6 Ґ
---- χ	ﻫ ﺍ ﻓ ﻩ N Ґ ﺍ ﻫ ﺍ ﻓ ﻩ N Ψ ק

Note:

BR:	Company Code.
C5345:	Product Type.
U=	h_{FE} Classifications Symbol.

( ) / Temperature Profile for Dip Soldering(Pb-Free)



ب ˝ χ

1 Ĺ ♬ □ ỷ 25 Ḱ 150 ł ı `H ڑ 60 Ḱ 90sec;

2 Š Ө □ ỷ 255 ° 5 ł ı `H ڑ `Y ﾊ ㎞ 5 ° 0.5sec;

3 ì ˙ Ⅵ ˛ ɔ ﻉ ỷ ㎞ 2 Ḱ 10 ł /sec.

Note:

1.Preheating:25~150 ł , Time:60~90sec.

2.Peak Temp.:255 ° 5 ł , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ł /sec.

/ Resistance to Soldering Heat Test Conditions

□ ỷ χ 270 ° 5 ł `H ڑ χ 10 ° 1 sec. Temp:270±5 Time:10±1 sec

/ Packaging SPEC.

ˈQ ţ ﾔ Ł / BULK

Package Type	Units					Dimension		(unit mm3)
	Units/Bag /	Bags/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Bag	Inner Box	Outer Box
TO-92	1,000	10	10,000	5	50,000	135×190	237×172×102	560×245×195
	1,000	10	10,000	10	100,000	135×190	237×172×102	560×245×375

ﾊ Ⅴ ﾔ Ł / AMMO

Package Type	Units					Dimension	(unit mm3)
	Units/tape /	Tape/Inner Box /	Rows/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Inner Box	Outer Box
TO-92	3,000	1	120	10	30,000	328×230×42	480×346×235 547×407×268

/ Notices